

CAPABILITIES



• = Fully Supported	ANSYS	ANSYS	ANSYS	ANSYS	ANSYS	ANSYS
 = Limited Capability 	Mechanical	Mechanical	Mechanical Pro	Autodyn	LS-DYNA	AIM
= Requires more than 1 product	Enterprise	Premium		····· ·		
STRUCTURES	•					
Geometric Idealization						
Spring	•	•		•	•	•
Mass	•	•	•	•	•	•
Damper	•	•		•	•	
Spar	•	•	•			
Beam	•	•	•	•	•	
Pipe/Elbow	•	•	•			
Shell - Thin	•	•	•	•	•	•
Layered Shell - Thin (Composite)	•	•		•	•	
Shell - Thick (Solid Shell)	•	•	•			
Layered Shell - Thick (Solid Shell)	•	•				
(Composite)	•	•				
2D Plane / Axisymmetric	•	•	•	•	•	
3D Solids	•	•	•	•	•	•
Layered 3D Solids (Composite)	•	•				
Infinite Domain	•	•	•	•	•	
2.5D	•	•				
Reinforced	•	•		•	•	
ROM	•					
Substructuring / Matrix	•					
Modeling Capabilities						
Contact - Linear	•	•	•	•	•	•
Contact - Nonlinear	•	•	•	•	•	•
Joints	•	•	•	•	•	•
Spot Welds	•	•	•	•	•	
Element Birth and Death	•	•				
Gasket Elements	•					
Rezoning and Adaptive Remeshing	•			•	•	
Materials						
Basic Linear Materials (Linear,	•	•	•	•	•	•
Anisotropic, Temperature Dependent).	-	-	-	-	-	-
Basic Nonlinear Materials (Hyper,						
Plasticity, Rate Independent,	•	•		•	•	
Isotropic, Concrete).						
Advanced Nonlinear Materials (Rate					-	
dependent, Anisotropic, Damage Models,	•			•	•	
Geomechanics Materials, Multiphysics).						
Field Dependent	•	•				
Reactive Materials	•			•		
Fracture Mechanics and Crack Growth	•					

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Material Designer	•					
Composite Materials						
Material Definitions	•	•		•	•	
Layers Definitions	•			•	•	
Solid Extrusion	•					
First-ply Failure	•	•				
Last-Ply failure	•					
Delamination	•			•	•	
Draping	•					
Structural Solver Capabilities						
Linear Static	•	•	•			•
Nonlinear Static	•	•	•			•
Pre-Stress effects, Linear perturbation	•	•	•			
Nonlinear Geometry	•	•	•	•	•	•
Buckling - Linear Eigenvalue	•	•	•			
Buckling - Nonlinear Post Buckling	•					•
Behavior	•	•	•		•	•
Buckling - Nonlinear Post Buckling	•	•				
Behavior- Arc Length						
Steady State Analysis applied to a	•					
Transient Condition						
Advanced Wave Loading	•					
Topology Optimization						
Structural Optimization	•	•	•			•
Modal Optimization	•	•	•			•
Thermal Loads	•	•	•			
Inertial Loads	•	•	•			
Optimized Design Validation	•	•	•			•
Manufacuring Constraints	•	•	•			
Stress Constraints	•	•				•
Symmetry	•	•	•			•
Lattice Optimization		•	•			
Overhang/Additive Constraints		•	•			
Multi Analysis						
Submodeling	•	•	•			
Data Mapping	•	•	•			•
Multiphysics Data Mapping	•	•				
Initial State	•	•		•	•	

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 Requires more than 1 product 	Enterprise	Premium	Prechanicat 110	Autodyn	L9 DINA	
Advanced Multi-Stage 2-D to	•	•				
3-D Analysis	•	-				
Vibrations						
Modal	•	•	•			•
Modal - Pre-Stressed	•	•	•			٠
Modal - Damped/Unsymmetric	•	•				
Transient - Mode-Superposition	•	•				
Harmonic - Mode-Superposition	•	•				
Harmonic - Full	•	•				
Spectrum	•	•				
Random Vibration	•	•				
Mistuning	•	•				
Rotordynamics	•	•				
Modal Acoustic	•					
Harmonic Acoustic	•					
Nonlinear Transient Dynamics						
Rigid Body Mechanisms	•	•				
Rigid Body Dynamics with CMS	•					
components for flexible bodies	•					
Full Transient	•	•		•	•	
CMS with Substructuring	•					
Explicit Dynamics						
FE (Lagrange) Solver	•			•	•	
Euler Solvers				•		
Meshless Solvers				•		
Implicit-Explicit Deformations	•			•	•	
Implicit-Explicit Material States	•			•		
Fluid-Structure Interaction (FSI)	•			•		
Mass Scaling	•			•	•	
Natural Fragmentation	•			•		
Erosion Based on Multiple Criteria	•			•	•	
De-Zoning				•	•	
Part Activation and Deactivation				•		
(Multi Stage Analysis)						
Remapping in Space				•		
Remapping Solution Methods				•		
Durability						
Stress-Life (SN)	•	•	•			•

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Strain-Life (EN)	•	•	•			•
Dang Van	D ¹					
Safety Factor	•	•	•			•
Adhesive Bond	D ¹					
Crack Growth Linear Fracture Mechanics						
Seam Weld	□ ¹		\square^1			
Spot Weld	□ ¹					
Thermo-mechanical Fatigue	D ¹					
Vibration Fatigue	□ ¹					
Virtual Strain Gauge Correlation	D ¹					
Python Scripting Customization	D ¹					
· · ·						
Wave Hydrodynamics						
Diffraction and Radiation	•					
Frequency & Time Domain Motions	•					
Analysis						
Moorings, Joints & Tethers	•					
Load Transfer to Structural Analysis	•					
ž						
Thermal						
Steady State Thermal	•	•	•			•
Transient Thermal	•	•	•			•
Conduction	•	•	•	•	•	•
Convection	•	•	•			•
Radiation to Space	•	•	•			•
Radiation - Surface to Surface	•	•	•			
Phase Change	•	•	•	•	•	
Thermal Analysis of Layered Shells and Solids	•	•				
Additional Physics						
1-D Thermal-flow	•	•	•			
1-D Coupled-field Circuits	•					
1-D Electromechanical transducer	•					
MEMS ROM	•					
Piezoelectric	•					
Piezoresistive	•					
Electroelastic	•					
Electromagnetic	•					
Vibro-acoustics	•					

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= Requires more than 1 product	Enterprise	Treimain				
Electro-Migration	•					
Diffusion-Pore-Fluid	•					
Diffusion-Thermal Structural-Electric	•					
Structural-Thermal-Electric-Magnetic	•					
1-Way Fluid-Structure Interaction	□ ²	D ²	□ ²			•
2-Way Fluid-Structure Interaction	D ²					
Optimization						
DesignXplorer Included	•	•	•	□ ³	□3	•
Parameters	•	•	•	•	•	•
Design Point Studies	•	•	•	•	•	•
Correlation Analysis	•	•	•	•		•
Design of Experiments	•	•	•	•		•
Sensitivity Analysis	•	•	•	•		•
Goal Driven Optimization	•	•	•	•		•
Six Sigma Analysis	•	•	•	•		•
Miscellaneous and Usability						
ANSYS SpaceClaim	•	□4	□4	□ ⁴	□4	•
ANSYS Customization Suite (ACS)	•	□5	□5	□ ⁵	□5	•
Support ACT Extensions	•	•	•	•	•	•
Command snippet support	•	•	•			•
Batch run capability	•	•	•	•	•	•
External Code Interfaces	•	•		•	•	
On the fly post processing	•	•	•		•	
CDB and 3rd party FE Model Import	•	•	•		•	
HPC - Structures						
	4 (DMP + SMP) MAPDL					
Supported Number of Cores	4 for Explicit 4 for RBD	4 (DMP + SMP)	4 (DMP + SMP)	4	1	4 (DMP + SMP) MAPDL
	4 for AQWA					
Parallel Solving on Local PC	•	•	•	•	•	•
Parallel Solving on Cluster	•	•	•	•	•	

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GPU Acceleration	☐ ⁶ MAPDL - Yes Explicit - No RBD - No Aqwa - No	D 6	D 6			

1 = ANSYS nCode DesignLife Products

2 = ANSYS Fluent

3 = ANSYS DesignXplorer

4 = ANSYS SpaceClaim

5 = ANSYS Customization Suite (ACS)

6 = ANSYS HPC, ANSYS HPC Pack or ANSYS HPC Workgroup

DMP = Distributed-memory parallel

SMP = Shared-memory parallel

MAPDL = Mechanical APDL Explicit = Autodyn

RBD = Rigid Body Dynamics

Aqwa = Aqwa

ANSYS CF					ANSYS CFD Enterprise						
	D Premium										
ANSYS	ANSYS	ANSYS	ANSYS	ANSYS	ANSYS	ANSYS Chemkin					
FLUENT	CFX	POLYFLOW	Forte	FENSAP-ICE	AIM	Enterpris					
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				ANSYS CF	D Enterprise		
	ANSYS CE	D Premium			_		
 ■ = Fully Supported ▲ = Limited Capability 	ANSYS	ANSYS	ANSYS	ANSYS	ANSYS	ANSYS	ANSYS Chemkin
Ended Capability Image of the second seco	FLUENT	CFX	POLYFLOW	Forte	FENSAP-ICE	AIM	Enterprise
· · · · ·							-
Internal Radiation - Participating Media Internal Radiation - Transparent Media	•	•	•		•		•
External Radiation	•	•	_			•	•
Solar Radiation & Load	•	•				•	•
Simplified Heat Exchanger Model	•	•					
Non-equilibrium Thermal Model	•						
Prorous Media	•						
	•						
Particles Flows (Multiphase)							
Coupled Discrete Phase Modeling	_	_		-			_
including Thin Wall Films	•	•		•	•		•
Macroscopic Particle Model	•				1		
Inert Particle Tracking (With Mass)	•	•					
Liquid Droplet (Incl. Evaporation)	•	•		•	•		•
Combusting Particles	•	•		•			•
Multicomponent Droplets	•	•		•	•		•
Discrete Element Model (DEM)	•						
Break-Up And Coalescence	•	•		٠	•		•
Erosion	•	•					
Free Surface Flows (Multiphase)							
Implicit VOF	•	•	•				
Explicit VOF	•		•				
Coupled Level Set/VOF	•	•			•		
Open Channel Flow And Wave	•	•	_		_		
Surface Tension	•	•		•	•		•
Phase Change	•	•		•	•		•
Cavitation	•	•		•	•		•
Cavitation where multiple fluids and	•						
non-condensing gases are present							
Discussed Multinhese Flame (Multinhe	>						
Dispersed Multiphase Flows (Multipha							
Mixture Fraction	•	•			+		
Eulerian Model including Thin	٠	•		•	•		•
Wall Films					+		
Boiling Model	•	•		•			•
Surface Tension	•	•		•			•
Phase Change	٠	•		٠	•		•
Drag And Lift	•	•		•	•		•
Wall Lubrication	•	•		•			•
Heat And Mass Transfer	•	•		•	•		•
Population Balance	•	•		•	1		•
Reactions Between Phases	•	•		•	+ +		•
Granular Model for Dense Bed of Solids	•	•		-	+ +		-
Dense Particulate Coupling (DDPM)	•	•			+ +		
	-	-					

				ANSYS CF	D Enterprise		
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Limited Capability	ANSYS	ANSYS	ANSYS	ANSYS	ANSYS	ANSYS	Chemkin
= Requires more than 1 product	FLUENT	CFX	POLYFLOW	Forte	FENSAP-ICE	AIM	Enterprise
Reacting Flows							
Species Transport	•	•	•	•			•
Non-Premixed Combustion	•	•		•			•
Premixed Combustion	•	•		•			•
Partially Premixed Combustion	•	•		•			•
Composition PDF Transport	•	•					
Finite Rate Chemistry	•	•	•	•			•
Pollutants And Soot Modeling	•	•		•			•
Sparse chemistry solver with dynamic							
cell clustering and dynamic adaptive	•			•			•
chemistry							
Ability to use Model Fuel Library							
mechanisms	•			•			•
Flame-speed from Fuel-component							•
Library	•			•			-
DPIK Spark-ignition Model				•			•
Flame-propagation using level-set				-			
method (G-equation)				•			•
Internal Combustion Engine							
Specific Solution	•	•		•			•
0-D/1-D/2-D reactor models and							
reactor networks							•
Plasma reactions							•
Comprehensive surface-kinetics	•						•
Chemical and phase equilibrium	•						•
Flamelet table generation	•						•
Flamespeed and ignition table							
generation							•
Reaction sensitivity, uncertainty							
and path analysis							•
Surrogate blend optimizer							•
Mechanism Reduction							•
Turbomachinery							
MRF/Frozen-Rotor	•	•					
Sliding-Mesh/Stage	•	•					
Transient Blade Row		•					
Pitch Change		•					
Time Transformation		•					
Fourier Transformation		•					
Harmonic Analysis		•					

				ANSYS CFE) Enterprise		
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= Limited Capability	ANSYS	ANSYS	ANSYS	ANSYS	ANSYS	ANSYS	Chemkin
= Requires more than 1 product	FLUENT	CFX	POLYFLOW	Forte	FENSAP-ICE	AIM	Enterprise
Blade Flutter Analysis		•					
Forced Response Analysis		•					
Flank milled blades		•					
In-Flight Icing							
Simulates Droplet Sizes					•		
Simulates Ice Growth and Performs					•		
Visibility Studies							
Models Heat Transfer Anti- and					•		
De-icing Heat Loads							
Rotating frame of reference for the							
analysis of turbomachines, rotors					•		
and propellers Model ice accretion at engine face							
(Fan and IGV) and within any number							
of successive compressor stages							
Aerodynamic degradation (CFD) meets							
the requirements of Appendix C,					•		
Appendix D (Ice Crystals) and							
Appendix O (SLD)							
Optimization							
Parameters	•	•	•			•	
Design Point Studies	•	•	•			•	
Correlation Analysis	•	•	•			•	
Design of Experiments	•	•	•			•	
Sensitivity Analysis	•	•	•			•	
Goal Driven Optimization	•	•	•			•	
Six Sigma Analysis	•	•	•			•	
Adjoint Solver for Shape Optimization	•						
Adjoint solver supports rotating							
reference frames & conjugate	•						
heat transfer							
Multi-objective-constrained optimization	•						
Mesh Morphing (RBF Morph)							
High Rheology Material							
Viscoelasticity			•				
Specialty Extrusion Models			•				
Specialty Blow Molding Models			•				
Specialty Fiber Spinning Models	•						
<u></u>	-	1	1		1		1

	ANSYS CFD Enterprise							
• = Fully Supported	ANSYS CF	D Premium			_		ANSYS	
= Limited Capability	ANSYS	ANSYS	ANSYS	ANSYS	ANSYS	ANSYS	Chemkin	
= Requires more than 1 product	FLUENT	CFX	POLYFLOW	Forte	FENSAP-ICE	AIM	Enterprise	
HPC – Fluids								
Parallel Solving On Local PC Option	•	•	•	•	•	•	•	
Parallel Solving Over Network Option	•	•	•	•	•	•	•	
GPU Support	•		•					
Pre and Post Processing								
Photo realistic rendering	•	•	•	•	•		•	
SpaceClaim Direct Modeler	•	•	•	•	•	•	•	
Compare multiple runs, datasets	•	•	•	•	•		•	
physics, graphs in a single window								
MULTIPHYSICS								
Advanced, Automated Data Exchange	•	•	•		•	•		
Accurate Data Interpolation Between	•	•			•	•		
Dissimilar Meshes								
Drag-n-Drop Multiphysics	•	•	•					
Direct Coupling Between Physics	•	•				•		
Collaborative Workflows	•	•				•		
Fully Managed Co-Simulation	•	•						
Flexible Solver Coupling Options	•	•			•			
Fluid-Structure Interaction								
Force Induced Motion/Deformation			•			•		
Fluid Thermal Deformation						•		
Electro-Thermal Interaction								
Convection Cooled Electronics	•	•						
Conduction Cooled Electronics	•	•						
High Frequency Thermal Management	•	•						
Electromechanical Thermal	•	•						
Management								
Other Coupled Interactions								
Aero-Vibro Acoustics	•							
Acoustics-Structural	•	•						
Fluid Magnetohydrodynamics	•	•						
Miscalleneous and Usability								
Support ACT Extensions	•							
Ansys Spaceclaim	-					•		
						-		



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ELECTRONICS						
Low Frequency Electromagnetics						
Electrostatics	•					•
AC Conduction	•					•
DC Conduction	•					•
Magnetostatics	•					•
Adaptive Field Mesh	•	•	•	•		•
AC Harmonic Magnetic	•					•
Electric Transient	•					
Magnetic Transient						
Translational Motion	•					
Fully Automatic Symmetrical	-					
Mesh Generation	•					
Rotational Motion	•					
Non-Cylindrical Motion	•					
Advanced Embedded Circuit Coupling	•					
Circuit Coupling with Adaptive	•					
Time Stepping	•					
Direct and Iterative Matrix Solvers	•					
Advanced Magnetic Modeling						
Vector Hysteresis Modeling	•					
Hysteresis Modeling for Anisotropic	•					
Material	•					
Frequency Dependent Reduced	•					
Order Models						
Equivalent Model Extraction	•					
(Linear-Motion, Rotational-Motion, No-Motion)	-					
Functional Magnetization Direction	•					
Magnetization/De-magnetization	•					
Modeling Manufacturing Dependent Core						
Loss Models	•					
Noise - Vibration Modeling	•					
Temperature De-magnetization						
Modeling	•					
Core Loss computation	•					•
Lamination Modeling	•					
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Magnetostriction and Magnetoelastic	•				
Modeling					
Hardware in the Loop modeling	•				
Integrated Motor Synthesis and	•				
Design Kit					
Integrated Planar Magnetics Synthesis and Design Kit	•				
Synthesis and Design Kit					
High Frequency Electromagnetics					
Multi-frequency broadband adaptive					
meshing		•			
Frequency, Integral Equation and					
Time Domain Analysis		•			
Eigenmode Analysis		•			
Hybrid Finite Element/Integral		•			
Equation Analysis		•			
Hybrid Finite Element/Shooting and					
Bouncing Ray Analysis		•			
Modal Wave Port Excitation		•			
Parametric Antenna Excitations		•			
for SBR+		•			
Lumped, Voltage and Current		•			
Excitations		•			
Floquet Excitations		•			
Incident Wave Excitation		•			
Magnetic Ferrite Bias Excitation		•			
Terminal Solutions		•			
Perfect Electric and Magnetic Boundary		•			
Finite Conductivity Boundaries		•			
Lumped RLC Boundary		•			
Symmetry Boundary		•			
Periodic Boundary		•			
Frequency dependant materials		•			
Higher and Mixed order Elements		•			
Curvilinear Elements		•			
Fully automated adaptive		•			
mesh refinement		•			
S,Y,Z Matrix Results		•			
E, H, J, P Field Results		•			
Direct and Iterative Matrix Solvers		•			

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· · ·					
Antenna Parameter Calculation		•			
Infinite and Finite Antenna Array		•			
Calculations					
Radar Cross Section calculation		•			
FSS, EBG and Metamaterial Calculation		•			
Specific Absorption Rate Calculation		•			
EMI/EMC Calculation		•			
System Level EMI and RFI analysis		•			
Linear Circuit Analysis with EM		•			
Dynamic link					
Integrated Antenna Synthesis and		•			
Design Kit					
Shooting and Bouncing Ray+		•			
(SBR+) Solver					
Integrated Parametric 3D		•			
Component Libraries					
RF Link Budget Analysis		•			
Wireless Propagation Models		•			
Visual Ray Tracing		•			
Power and Signal Integrity					
Board Simulation Capabilities					
Electronics Desktop 3D Layout GUI		•	•		•
ECAD Translation (Altium, Cadence,		•	•		
Mentor, Pulsonix, & Zuken)					
MCAD (.sat) Generation from ECAD		•	•		
Lead Frame Editor		•	•		
DC Voltage, Current and Power			•		
Analysis for PKG/PCB					
DC Joule Heating with ANSYS Icepak			•	•	•
Passive Excitation Plane Resonance			•		
Analysis					
Driven Excitation Plane Resonance			•		
Analysis					
Automated Decoupling Analysis			•		
Capacitor Loop Inductance Analysis			•		
AC SYZ Analysis - PI, SI, & EMI		•	•		
Dynamically Linked Electromagnetic		•	•		
Field Solvers		-			

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Chip, Package, PCB Analysis (CPM)		•	•		
Near-Field EMI Analysis			•		
Far-Field EMI Analysis			•		
Characteristic Impedance (Zo)					
PKG/PCB Scan			•		
Full PCB/PKG Cross-talk Scanning			•		
TDR Analysis		•	•		
Transient IBIS Circuit Analysis			•		
SerDes IBIS-AMI Circuit Analysis			•		
Macro-Modeling (Network Data Explorer)		•	•	•	
Steady State AC (LNA) Analysis		•	•		
Virtual Compliance - DDRx, GDDRx,			•		
& LPDDRx			•		
Synopsys HSPICE Integration			•		
Cadence PSPICE Support			•		
Electromagnetically Circuit Driven		•	•		
Field Solvers					
RLCG Parasitic Extraction					
DCRL, ACRL & CG Solver			•	•	
IC Packaging RLCG IBIS Extraction			•	•	
for Signals & Power					
Touchpanel RLCG Unit Cell Extraction			•	•	
Adaptive Meshing for Accurate			•	•	
Extraction					
Bus Bar RLCG Extraction				•	
Power Inverter & Converter				•	
Component Extraction Specialized Thin Plane Solver for					
Touchpanel Extraction				•	
3D Component Library		•		•	
Reduced RLCG Matrix Operations				•	
SPICE equivalent Modeling Export				•	
DCRL & ACRL Joule Heating Analysis					
with Icepak				•	
Macro-modeling (Network Data Explorer)				•	
2D Transmission Line Modeling Toolkit				•	
2D Cable Modeling Toolkit				-	
				•	

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= Limited Capability	Maxwell	HFSS	SIwave	Q3D Extractor	Icepak
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Electronics Cooling					
Multi-mode Heat Transfer					•
Steady-state and Transient					•
CFD Analysis					•
Turbulent Heat Transfer					•
Multiple-fluid Analysis					•
Species Transport					•
Solar Loading					•
Reduced Order Flow and Thermal					•
Network Modeling					•
Joule Heating Analysis					•
Thermo-electric Cooler Modeling					•
Thermostat Modeling					•
Package Characterization					•
Data Center Modeling					•
HPC for Electronics					
GPU Support					
HPC Accelerated Frequency Sweeps			•		
HPC Distributed Hybrid Solving		•			
HPC Enabled Domain Decomposition		•			
Method					
HPC Time Decomposition Method	•				
HPC Enabled Multi-port Excitation		_			
Acceleration		•			
HPC Acceleration for DCRL, ACRL				_	
and CG				•	
HPC Enabled Parallel Processing	•	•		•	•
SYSTEMS MODELING -					
ELECTRONIC PRODUCTS					
System Modeling for Power Electronics					
Circuit Simulation	•	•	•	•	•
Block Diagram Simulation	•	•	•	•	•
State Machine Simulation	•	•	•	•	•
VHDL-AMS Simulation	•	•	•	•	•
Integrated Graphical Modeling	_		•		•
Environment	•		•	•	•
Power Electronics Component Libraries	●	•	•	•	•
Reduced Order Modeling	•	•	•	•	•

 ■ Fully Supported ▲ = Limited Capability ■ = Requires more than 1 product 	ANSYS Maxwell	ANSYS HFSS	ANSYS SIwave	ANSYS Q3D Extractor	ANSYS Icepak
Power Electronic Device and Module Characterization	•	•	•	•	•
Co-Simulation with MathWorks Simulink	•	•	•	•	•
System Modeling for RF/Microwave					
Radio Frequency Interference (RFI) System Solver					
Electromagnetic Interference System Solver					
RF Link Budget Analysis					
RF co-site and antenna coexistence analysis					
Automated diagnostics for rapid root-cause analysis					
RF component library					
Wireless Propagation Models					
Multi-fidelity parametric radio models					
Antenna-to-Antenna coupling models					
System Modeling for SI/PI					
SerDes channel modeling - IBIS-AMI, QuickEye and VerifEye			•		
Multi-drop & parallel bus modeling - IBIS, HSPICE, Spectre, PSPICE, and Nexxim Transient			•		
Network Data Exploration		•	•	•	
TDR analysis			•		
Steady State AC (LNA) Analysis			•		
Virtual Compliance - DDRx, GDDRx, & LPDDRx			•		

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MULTIPHYSICS					
Platform Technologies					
Advanced, Automated Data Exchange	•	•		•	•
Accurate Data Interpolation Between	•	•		•	•
Dissimilar Meshes	•	•		•	•
Drag-n-Drop Multiphysics	•	•		•	•
Direct Coupling Between Physics	•	•		•	•
Collaborative Workflows	•	•		•	•
Fully Managed Co-Simulation	•	•		•	•
Flexible Solver Coupling Options	•	•		•	•
Electro-Thermal Interaction					
Convection Cooled Electronics		•			•
Conduction Cooled Electronics		•			•
High Frequency Thermal Management		•		•	•
Electromechanical Thermal Management	•			•	•
Miscellaneous					
Support ACT Extensions					

ANSYS[®]

 = Fully Supported 	ANGVC				Madini
= Limited Capability	ANSYS Twin Builder	ANSYS SCADE	ANSYS SCADE	ANSYS SCADE	Medini
= Requires more than 1 product	Twill Builder	Architect	Suite	Display	Analyze
SYSTEMS & EMBEDDED SOFTWARE					
System Simulation, Validation and					
Digital Twins					
Integrated Graphical Modeling	_				
Environment	•				
Standard Modeling Languages and	•				
Exchange Formats	•				
Multi-domain Systems Modeler	•				
Extensive OD Application-Specific	•				
Libraries	-				
3rd Party (1D) Tool Integrations	•				
3D ROM	•				
Embedded Software Integration	•				
Multi-domain System Simulation	•				
Rapid HMI Prototyping	•				
System Optimization	•				
XIL Integration	•				
IIoT Connectivity	•				
Digital Twin Runtime Deployment	•				
Functional Cofety Analysis					
Functional Safety Analysis					_
Safety Concept Modelling					•
Model Based Safety Analysis					•
Reliability Prediction and Analysis					•
Traceability and Validation Teamwork					•
Integration into Engineering					
Environment					•
Customization and Process Adaption					•
ANSYS Product Integration					•
Reporting and Documentation					•
					•
Model-based Systems Engineering					
Model-Based System Design		•			
Functional Safety Analysis		•			
Functional Decomposition		•			
Architecture Decomposition		•			
Allocation Of Functions To					
Components		•			
Model Checks		•			
System Model Diff/Merge		•			
System / Software Bi-Directional Sync		•			
Model Sharing And IP Protection		•			
Model-Based Interface Control		•			
Document Production		-			
Configurable For Industry Standards		•			
(IMA, AUTOSAR, Etc.)					

 ■ Fully Supported ▲ = Limited Capability ■ = Requires more than 1 product 	ANSYS Twin Builder	ANSYS SCADE Architect	ANSYS SCADE Suite	ANSYS SCADE Display	Medini Analyze
Product configuration for automotive developers		•			
Embedded Control Software Development					
Data Flow And State Machine Design And Simulation Capabilities			•		
Extensive Set Of Libraries Delivered As Design Examples			•		
Simulation Capabilities			•		
Record And Playback Scenarios Integration In To Configuration			•		
Management Environment			-		
Plant Model Co-Simulation Including FMI			•		
Coverage Analysis For Requirements- Based Tests			•		
Formal Verification			•		
Timing And Stack Optimization			•		
Worst Case Execution Time Estimates On Target			•		
Verification Of Stack Space Requirements			•		
Certified Code Generation For DO-178C, EN 50128, ISO 26262, IEC 61508			•		
Certification Kits For DO-178C, EN50128, ISO 26262, IEC 61508			•		
Man-Machine Interface Software Model-Based Prototyping And					
Specification Of MMIs				•	
Support Of OpenGl, OpenGl SC and OpenGL ES				•	
Integration In To Configuration				•	
Management Environment					
Font Management				•	
Optimization Of Graphical Specifications Plant Model Co-Simulation Including				•	
FMI Automatic Generation Of iOS and					
Android Projects				•	
Certified Code Generation For DO-178C, EN 50128, ISO 26262, IEC 61508				•	
Certification Kits For DO-178C, EN50128, ISO 26262, IEC 61508				•	
Testing capabilities				•	



 ■ = Fully Supported ▲ = Limited Capability ■ = Requires more than 1 product 	ANSYS Design Modeler	ANSYS SpaceClaim Direct Modeler
GEOMETRY		
Direct Modeling Technology		•
Feature Based Modeling Technology	•	
Open data from all major	_	
CAD systems	•	•
Export data to neutral file formats	•	•
Modify imported geometry	•	•
Defeaturing and simplification tools	•	•
Model Repair	•	•
Add Parameters for design exploration	•	•
Extract mid-surfaces/shells and beams	•	•
Extract volumes & create inner fluid domains	•	•
Extract outer air enclosures	•	•
Shared Topology for conformal meshing	•	•
Booleans and slicing	•	•
Create weld bodies	•	•
Boundary condition mapping	•	•
Scripting	•	•
Sketching and editing tools	•	•
3D comparison tools		•
Repair and edit faceted data		•
Icepak integration	•	•
Reverse engineering faceted data		•

NNSYS[®]

 = Fully Supported 	ANSYS	ANSYS	ANSYS
Limited Capability	Discovery	Discovery	Discovery
= Requires more than 1 product	Essentials	Standard	Ultimate
DESIGN TOOLS			
Structural			
Static Structural Analysis		•	•
		_	-
Modal Analysis		•	•
Pre-Stressed Modal Analysis			•
Shells, Springs, Point Masses			•
Spatially Varying Loads			•
Nonlinear Contact & Joints			•
Pre-tension Bolts & Multi-step			•
Analsysis			
Basic Plasticity			•
Large Deformation			•
Fatigue Analysis			•
Topology Optimization			•
Fluid			
Steady-State Flow		•	•
Transient Flow		•	•
Time-dependent Fluid Conditions			•
Incompressible Flow			•
Compressible Flow ¹			•
Non-Newtonian Fluids			•
Periodic Domains			•
Porous Media			•
Particle Flow			•
Thermal			
Steady State Thermal		•	•
Transient Thermal		•	•
Time Dependent Thermal Conditions			•
Conduction		•	•
Convection		•	•
Radiation to Space			•
			-
Electromagnetics			
DC Conduction			•
AC Conduction			•
Electrostatics			•
Magnetostatics			•
AC Harmonic Magnetics			•
			-

Multiphysics • Thermal-stress •	
Fluid-structure interaction •	
Fluid-solid thermal	
(conjugate heat transfer)	
Thermal-electric •	
Thermal-electric-stress •	
Thermal-electromagnetic •	
Thermal-electromagnetic-stress •	
Design & Concept Modeling	
Concept Modeling or Detail Design	
Part/Assembly Creation or Import••Large Assembly Importing••	
Geometric Parameterization • • • •	
Manufacturing	
Repair & Defeature Tools • •	
Sheet metal editing and	
unfolding	
3-D Printing ²	
Import, repair, edit faceted data	
Shelling and infills • • Thickness detection • •	
Reverse Engineering	
Autosurface of scanned data	
Build solid/surfaces on scanned data	
Interfaces and Addons	
Catia/JT translator • •	
Algoryx Momentum ³ • •	
Keyshot rendering ³ • •	

Notes: (1) Discovery Live supports mildly compressible fluid flow up to ~Mach 0.3 (2) Included with Discovery Standard and Ultimate (3) Add-on Module

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ADDITIVE PRINT			
Topology and Lattice Optimization			
Structural Optimization			•
Modal Optimization			•
Thermal Loads			•
Inertial Loads			•
Optimized Design Validation			•
Manufacturing Constraints			•
Stress Constraints			•
Symmetry			•
Lattice Optimization		•	
Overhang/Additive Constraints		•	
Geometry and STL file handling			
SpaceClaim Direct Modeler	•	•	•
Workbench Additive			
Nonlinear And Temperature		•	
Dependent Material Properties		•	
Thermo-Mechanical Coupled		•	
Strain Solution		-	
Native Mechanical Environment		•	
Stress-based Automatically		•	
Generated Supports		-	
Part Distortion & Residual Stress		•	
(as-built)		-	
Part Distortion & Residual Stress			
After Support Removal		•	
Distortion Compensation		•	
Blade Crash Detection		•	
Identification Of High Strain (Crack)		•	
Locations			
Layer By Layer Stress & Distortion		•	
Visualizations			
Additive Print			
Nonlinear and Temperature Dependent			
Material Properties	•	•	
Uniform Assumed Isotropic Strain	•	•	
Scan Pattern Based Anisotropic Strain	•	•	
Thermal Ratcheting Based Anisotropic Strain	•	•	

	Additive Print	Additive Suite*	Mechanical Enterprise
Desktop & Cloud Stand-Alone Environments	•	•	
Stress-based Automatically Generated Supports	•	•	
Part Distortion & Residual Stress (as-built)	•	•	
Part Distortion & Residual Stress After Support Removal	•	•	
Distortion Compensation	•	•	
Blade Crash Detection	•	•	
Identification Of High Strain (Crack) Locations	•	•	
Layer By Layer Stress, Distortion & Blade Crash Visualizations	•	•	
Build File Readers For Multiple AM Machines	•	•	
Additive Science (beta)			
Nonlinear and Temperature Dependent		•	
Material Properties		•	
Meltpool Dimensions		•	
Detailed Thermal History		•	
% Porosity		•	
Sensor Measurement Predictions		•	

* Additive Suite requires a Mechanical Enterprise license

• = Fully Supported	
 Fully Supported Limited Capability 	ANSYS Speos
 Requires more than 1 product 	
· · ·	
OPTICS	
Photometry Internation	
Intensity Illuminance	•
Luminance	•
3D Illuminance	•
	•
3D Energy Density	•
Human Vision	
Dynamic Adaptation	•
Glare Simulation	•
Wavelength Range	
UV-FIR (50nm–100µm)	
Optical Design	
Parabolic Surface	•
TIR Lens	•
Projection Lens	•
Optical Lens	•
Optical Surface	•
Light Guide	•
Sharp Cut-Off Reflector	•
Poly-Ellipsoidal Surface	•
Micro Optical Stripes	•
Optical Sensors	
Field Of View	•
Camera Sensor	•
LiDAR Sensor	•
Sensor Fusion	•
	-
Head-up Display	
HUD Optical Analysis	•
HUD Optical Design	•
HUD Visualisation	•
Manufactruing Variation	
Target Specification	•
Tolerance Study	•

 ● = Fully Supported ▲ = Limited Capability □ = Requires more than 1 product 	ANSYS Speos
Solver	
Multi-Threading	•
Highly Scalable HPC	•
Add-on Features	
Optimizer	•
Design of Experiment	•
Regulation Check	•
Colorimetry	•
Light Expert	•
3D Textures	•
3D Energy Density	•
Polarization	•
Fluorescence	•
360° view	•
Sky	•
Visibility & Legibility	•
Stray Light Analysis	•
High Dynamic Range Screen support	•
Virtual BSDF Bench	•
Thermic Source	•
MODTRAN Interface	
Night Vision Goggle	●



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